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In re patent application of

Kikuta, K.

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Washington, D.C. 20231

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SUBMISSION OF FORMAL DRAWINGS

Sir:

Submitted herewith are twenty-one (21) sheets of formal drawings comprising figures 1A - 6D for the above-identified patent application. Please substitute these formal drawings for the drawings which were filed with the application.

Respectfully submitted,

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FIG. 1A prior art

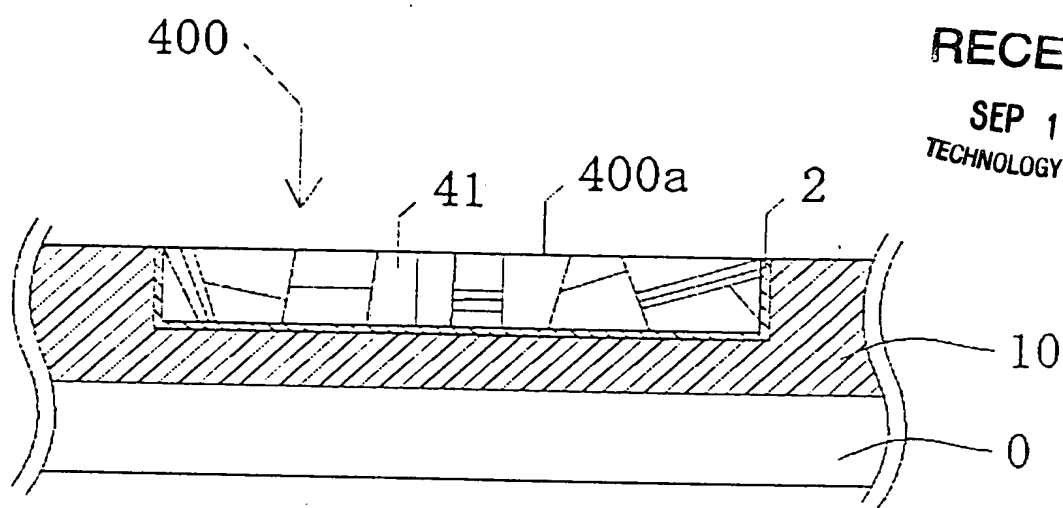


FIG. 1B prior art

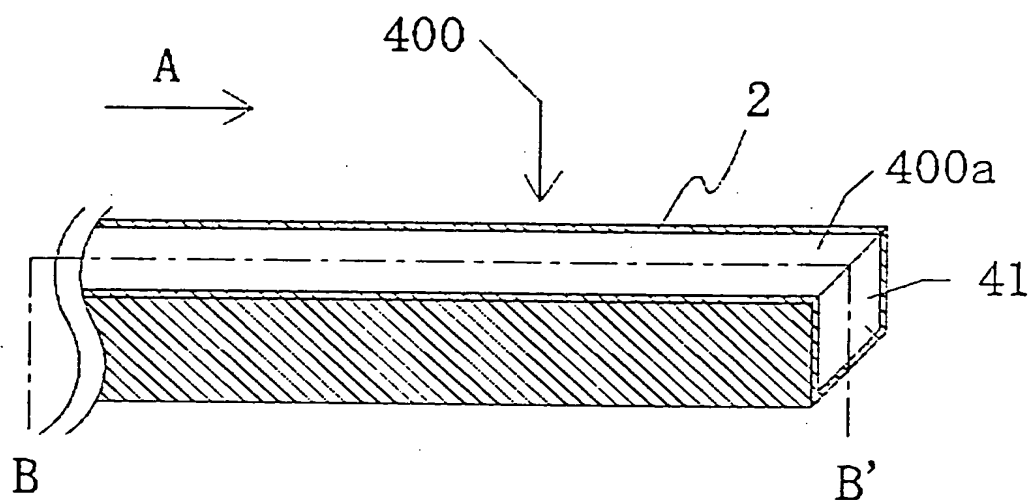


FIG. 1C prior art

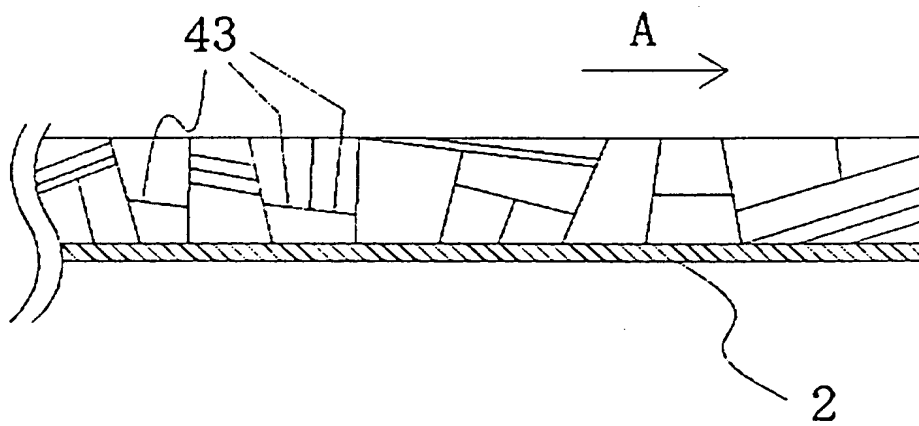


FIG. 2A prior art

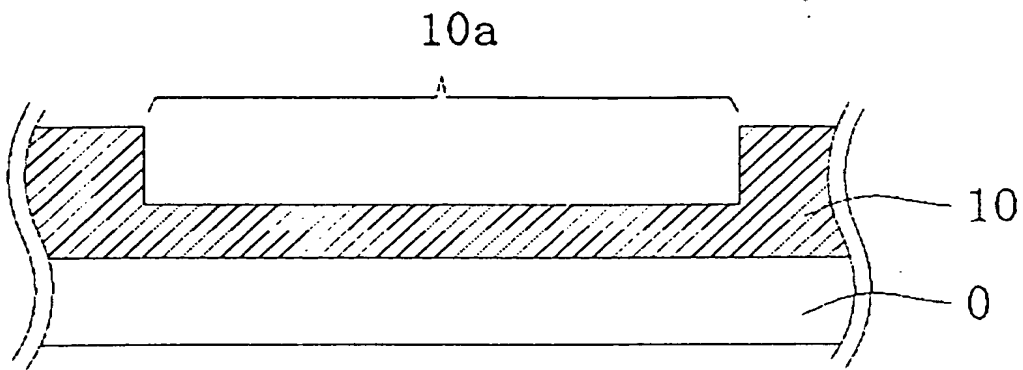


FIG. 2B prior art

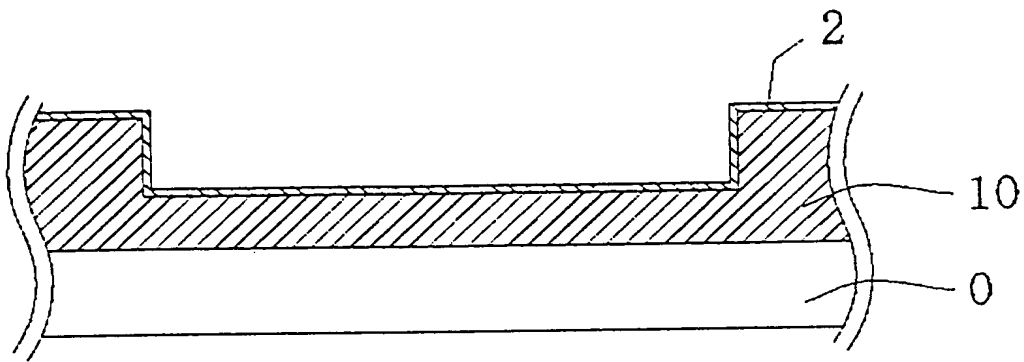


FIG. 2C prior art

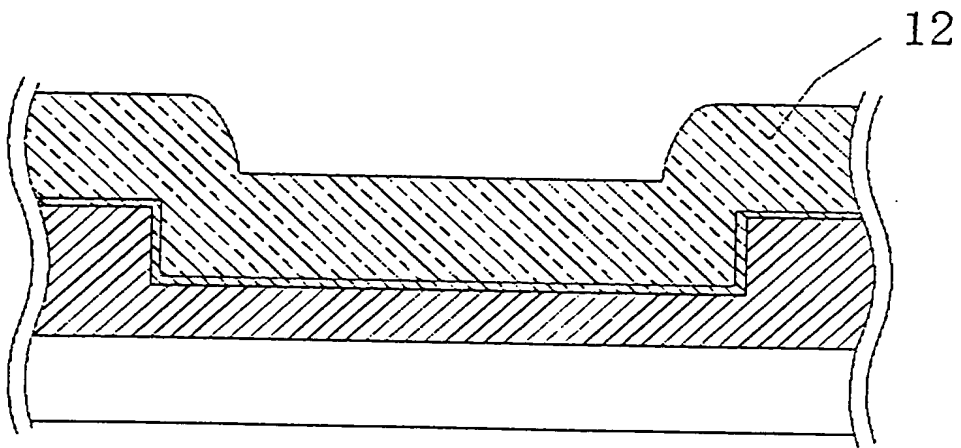


FIG. 2D prior art

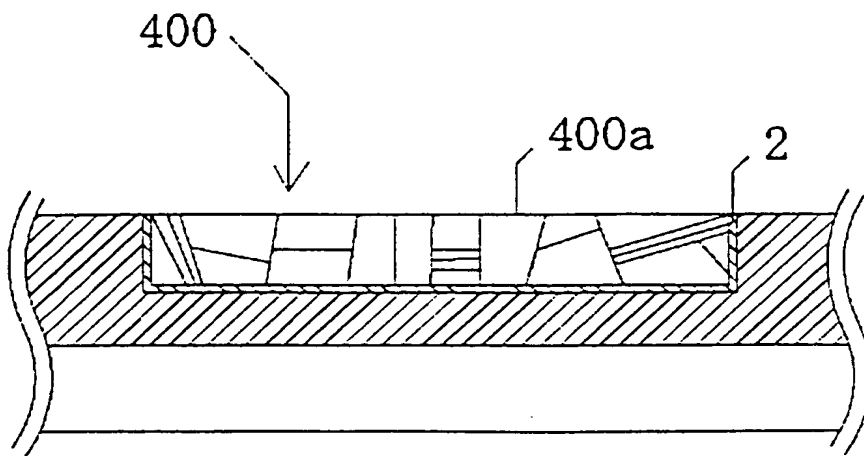


FIG. 3A

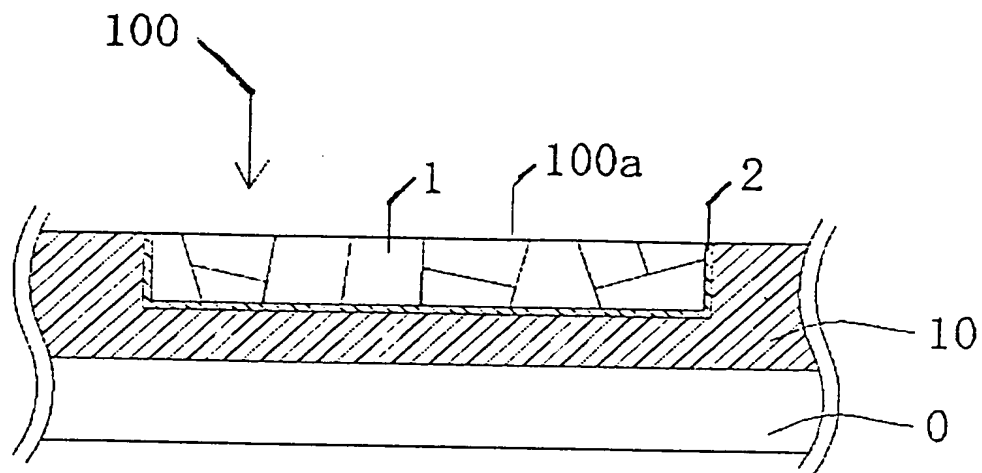


FIG. 3B

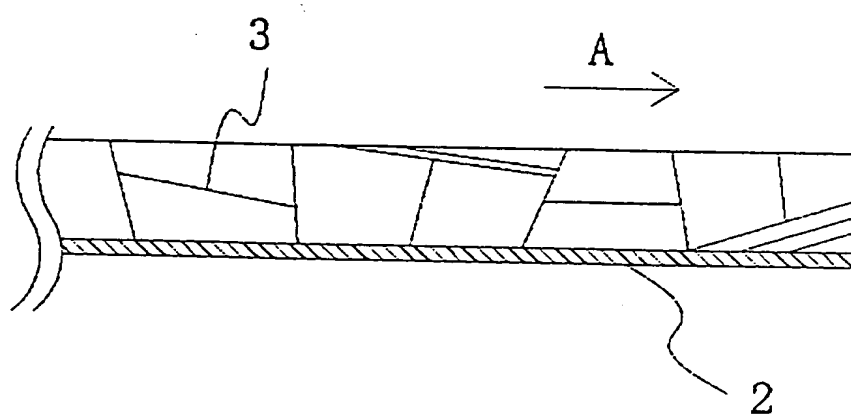


FIG. 3C

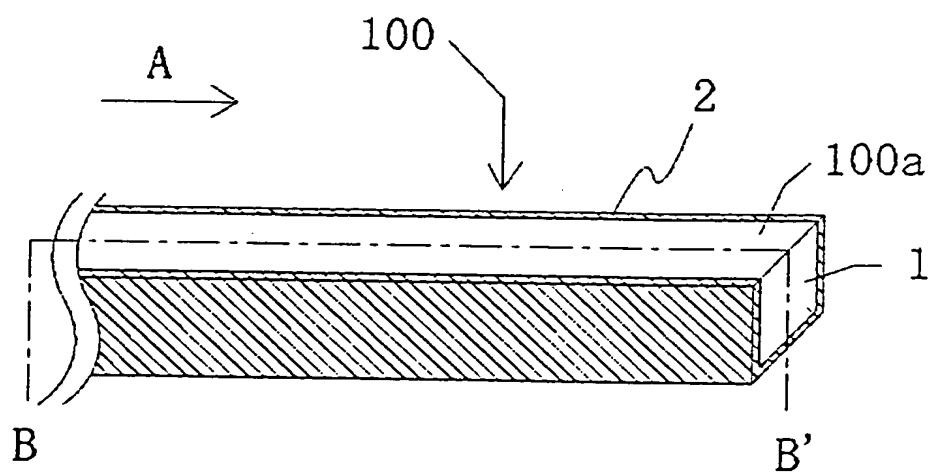


FIG. 3D

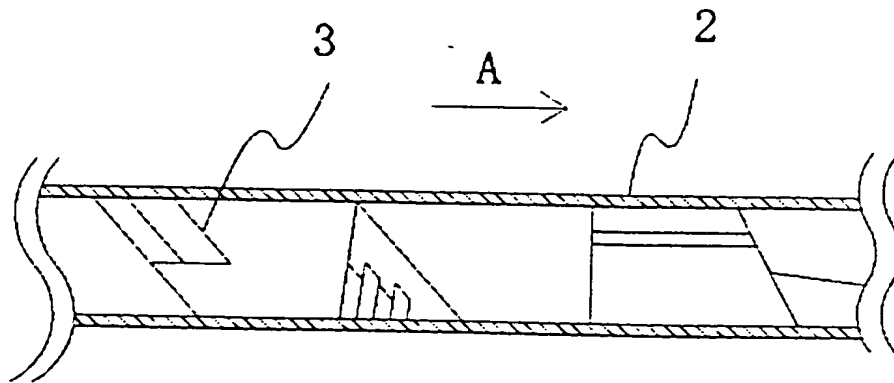
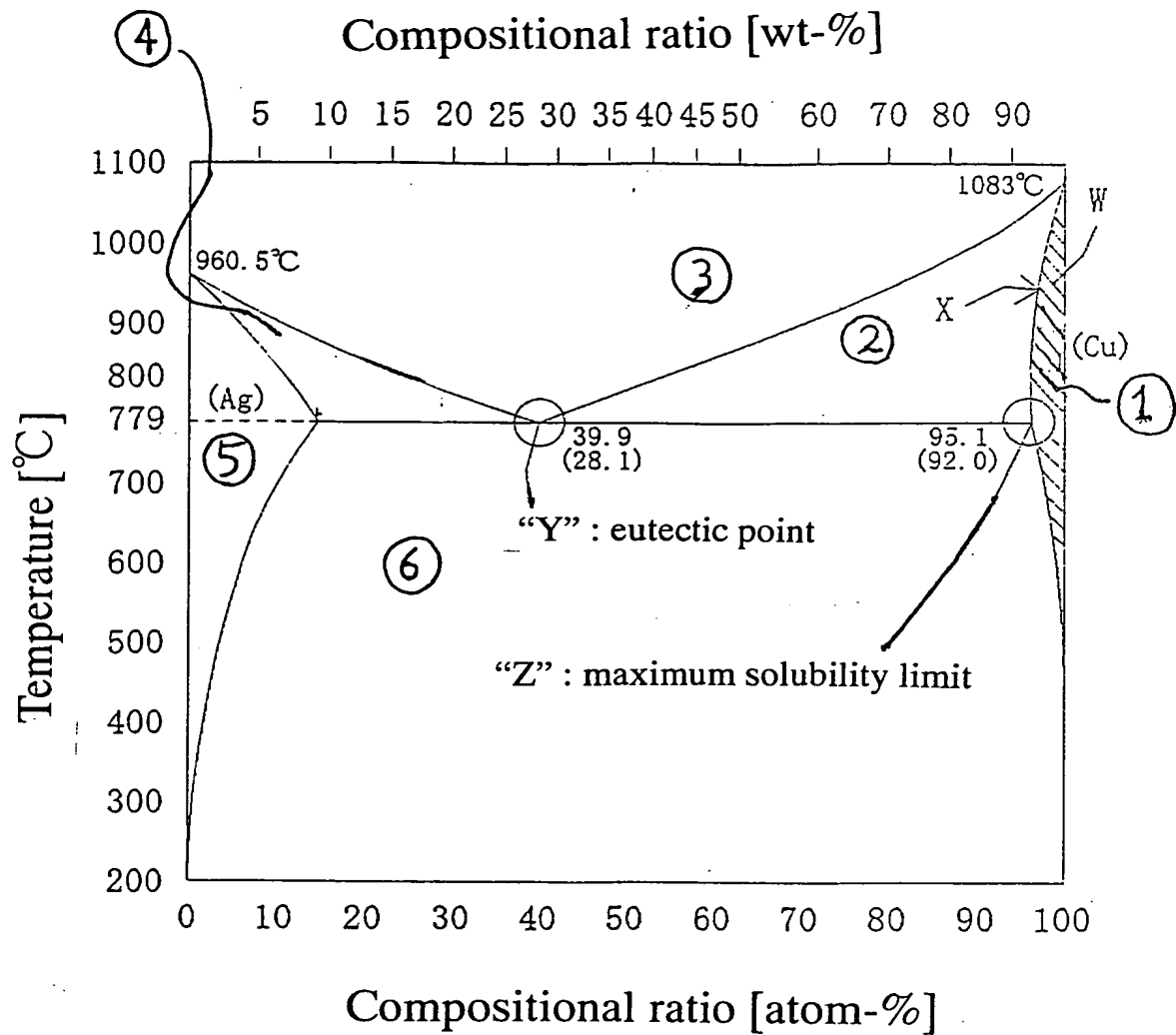


FIG. 4



- ① : a solid phase of Cu.
- ② : co-existence of a liquid phase of Ag and Cu and a solid phase of Cu.
- ③ : a liquid phase of Ag and Cu.
- ④ : co-existence of a liquid phase of Ag and Cu and a solid phase of Ag.
- ⑤ : a solid phase of Ag.
- ⑥ : a solid phase of Ag and Cu.

FIG. 5A

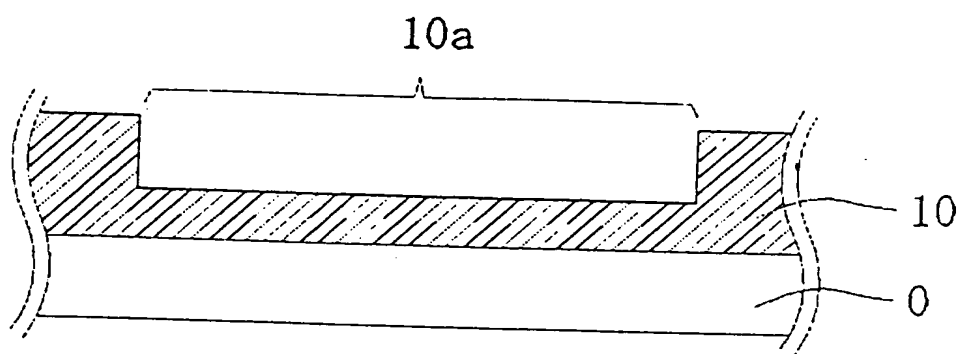


FIG. 5B

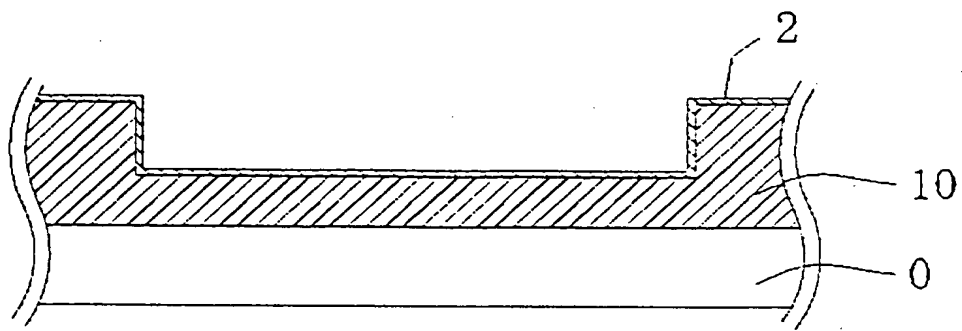


FIG. 5C

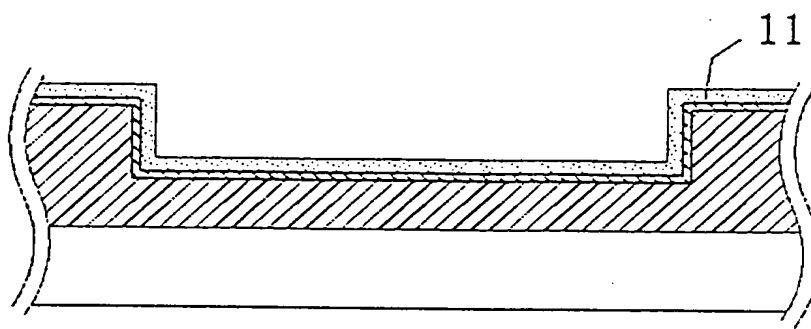


FIG. 5D

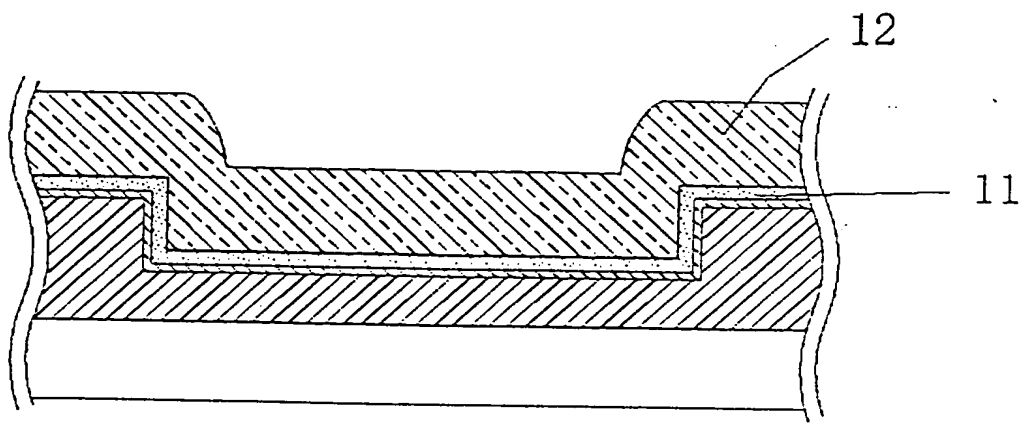


FIG. 5E

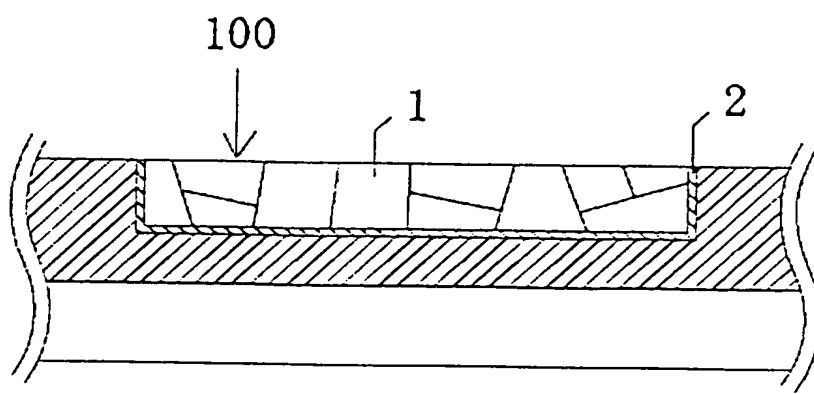


FIG. 6A

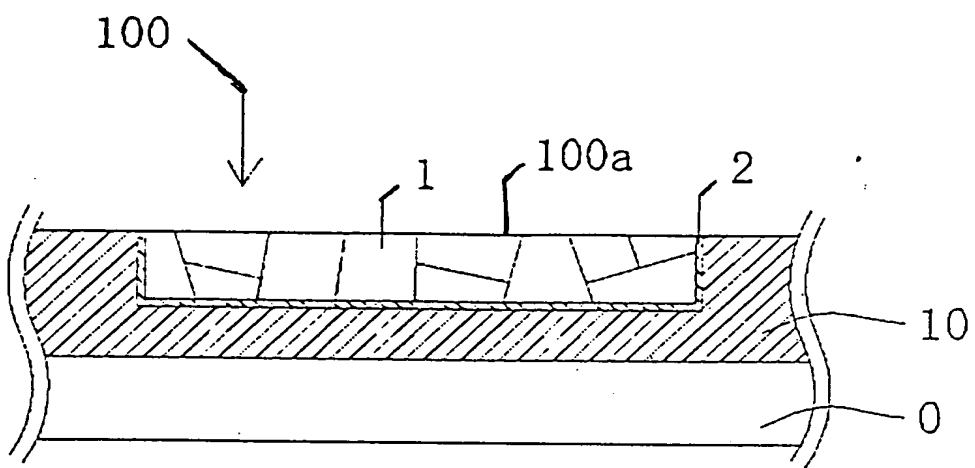


FIG. 6B

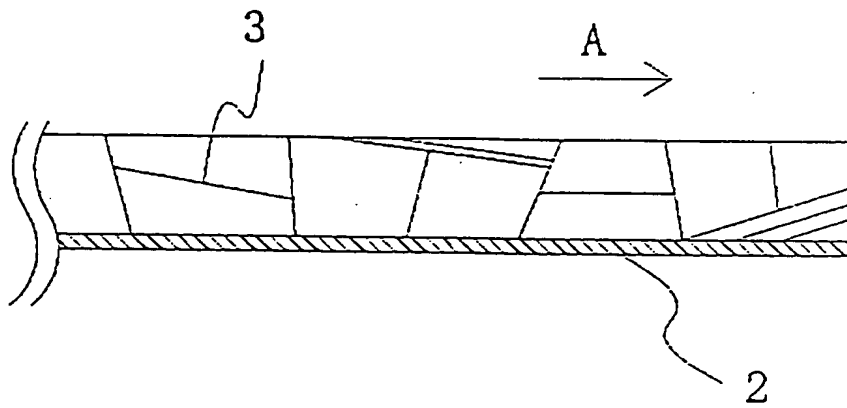


FIG. 6C

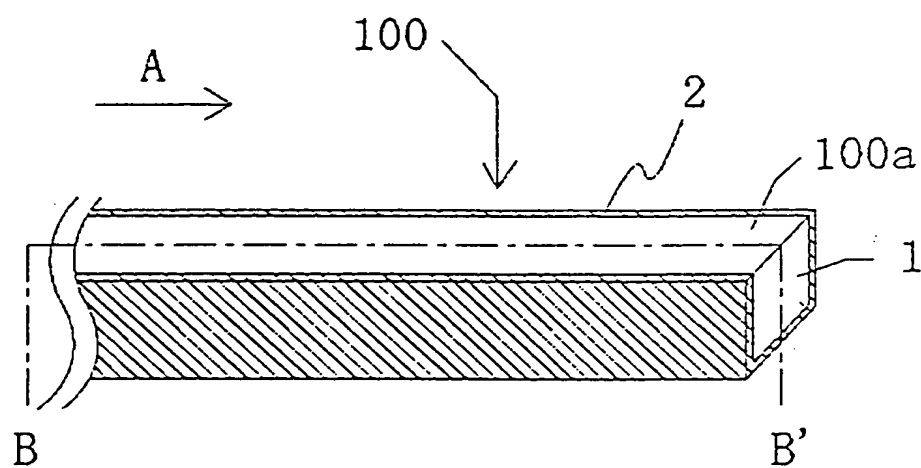


FIG. 6D

